XC9516 Series

ETR0707-009

Triple Output Power Supply for TFT-LCD

■GENERAL DESCRIPTION

☆GreenOperation Compatible

The XC9516 series can offer three different power supplies to TFT-LCD panels. These power supplies consist of a step-up DC/DC converter for a source driver, positive and negative charge pumps for a gate driver.
This IC has power-on sequences to keep inrush current as small when output voltage rises. The step-up DC/DC output can be used as power-on sequences with adding a P-channel FET as external component. Also, the FET can shut down a path to the power input line when CE pin is low.

■APPLICATIONS

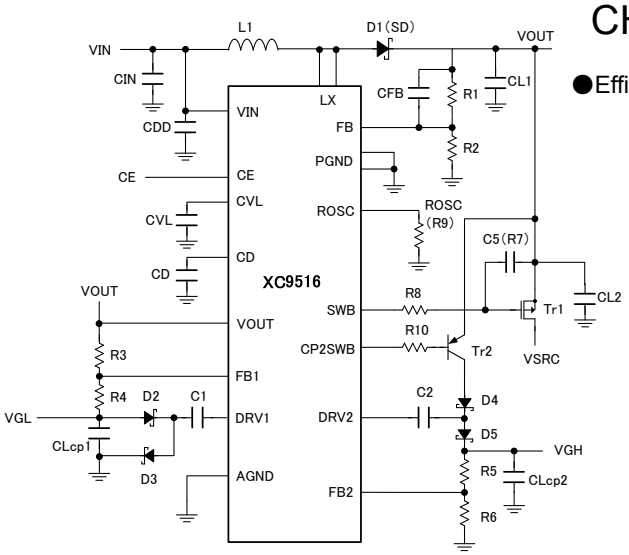
- TFT-LCD panels
- LCD monitors

■FEATURES

A Step-up DC/DC Converter and 2 of Charge Pumps (Positive/Negative)

Input Voltage Range	:	2.5V ～ 5.5V
Maximum Output Voltage	:	19V (DC/DC output)
Output Voltage Accuracy	:	±1.5%
Oscillation Frequency	:	300kHz ～ 1.2MHz (Adjustable)
External MOSFET Gate Signal Output	:	N-Channel Open Drain
Switch Over-Current Protection	:	1.3A
Soft-Start Time	:	Internally fixed
Protection	:	Over Voltage Protection (Step-up DC/DC 21V) Short-Circuit Protection (Step-up DC/DC) Short-Circuit Protection (Positive and Negative Charge Pump) Thermal Shutdown (150℃) UVLO (1.87V)
Operating Ambient Temperature	:	-40℃～+85℃
Package	:	QFN-20
Environmentally Friendly	:	EU RoHS Compliant, Pb Free

■TYPICAL APPLICATION CIRCUITS

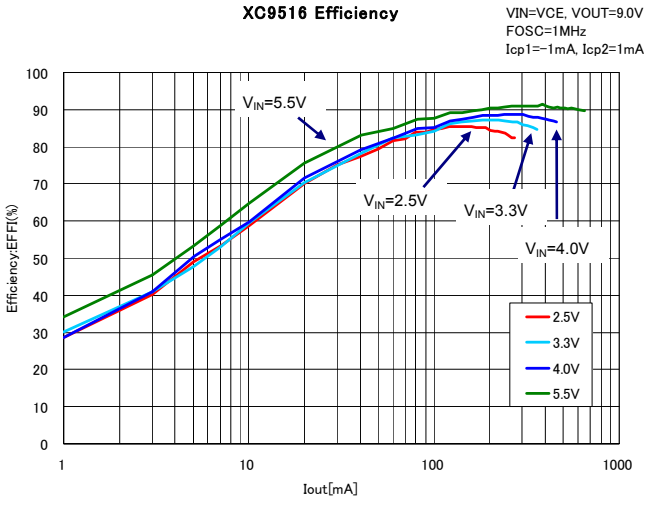


e.g) Components List

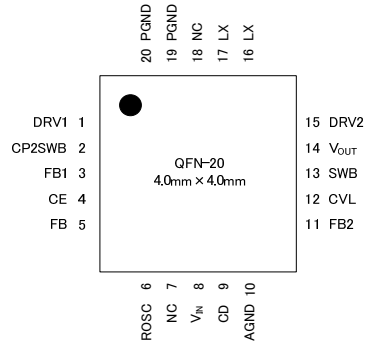
V_{OUT} = 9.2V, V_{GL} = -5.3V, V_{GH}= 12V	R_1 = 820 kΩ
C_{IN} = 4.7μF	R_2 = 100 kΩ
C_{L1},C_{L2} =4.7μF	R_3 = 390 kΩ
C_1, C_2 = 0.01μF	R_4 = 300 kΩ
C_{VL},C_D = 0.1μF	R_5 = 820 kΩ
C_{DD} = 1μF	R_6 = 75 kΩ
C_{Lcp1},C_{Lcp2} = 1μF	R_8 = 300 kΩ
C_{FB} = 22pF	R_{OSC} (R9) = 130 kΩ
C_5 = 0.01μF	R_{10} = 51 kΩ

■TYPICAL PERFORMANCE CHARACTERISTICS

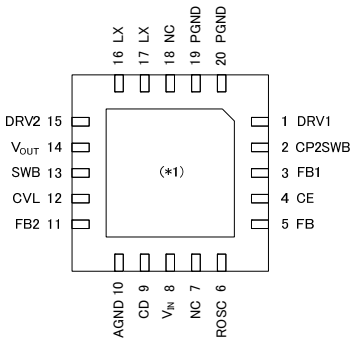
●Efficiency vs. Output Current



■PIN CONFIGURATION



＜TOP VIEW＞



＜BOTTOM VIEW＞

*1 The dissipation pad : AGND Level
（If the pad needs to be connected to other pins, it should be considered about the level of pad voltage.）

■PIN ASSIGNMENT

PIN NUMBER QFN-20	PIN NAME	FUNCTIONS
1	DRV1	Negative Charge Pump Driver Output
2	CP2SWB	Positive Charge Pump for Output Control
3	FB1	FB Pin for Negative Charge Pump
4	CE	Chip Enable Pin
5	FB	FB Pin for Step-Up DC/DC Converter
6	ROSC	Frequency Setting
7	NC	No Connection
8	V_{IN}	Power
9	CD	Short Protection Delay Capacitor Connection
10	AGND	Analog Ground
11	FB2	FB Input for Positive Charge Pump
12	CVL	Internal Power Capacitor Connection
13	SWB	Step-Up DC/DC Converter Output Control
14	V_{OUT}	Step-Up DC/DC Converter Output Voltage
15	DRV2	Positive Charge Pump Driver Output
16	L_X	Driver Output Pin for Step-Up DC/DC Converter
17	L_X	Driver Output Pin for Step-Up DC/DC Converter
18	NC	No Connection
19	PGND	Power Ground Pin for Driver
20	PGND	Power Ground Pin for Driver

■LOGIC CONDITION

PIN NAME	LOGIC	CONDITION
CE PIN	L	$GND \leqq V_{CE} \leqq 0.4V$
	H	$1.2V \leqq V_{CE} \leqq V_{IN}$

Voltage is based on V_{SS}（GND=AGND=PGND）

■FUNCTION CHART

CONDITIONS	IC OPERATION
L	OFF(Stand-by)
H	ON

IC operation is unstable when CE opens so that these pins shall not be left open outside.

■PRODUCT CLASSIFICATION

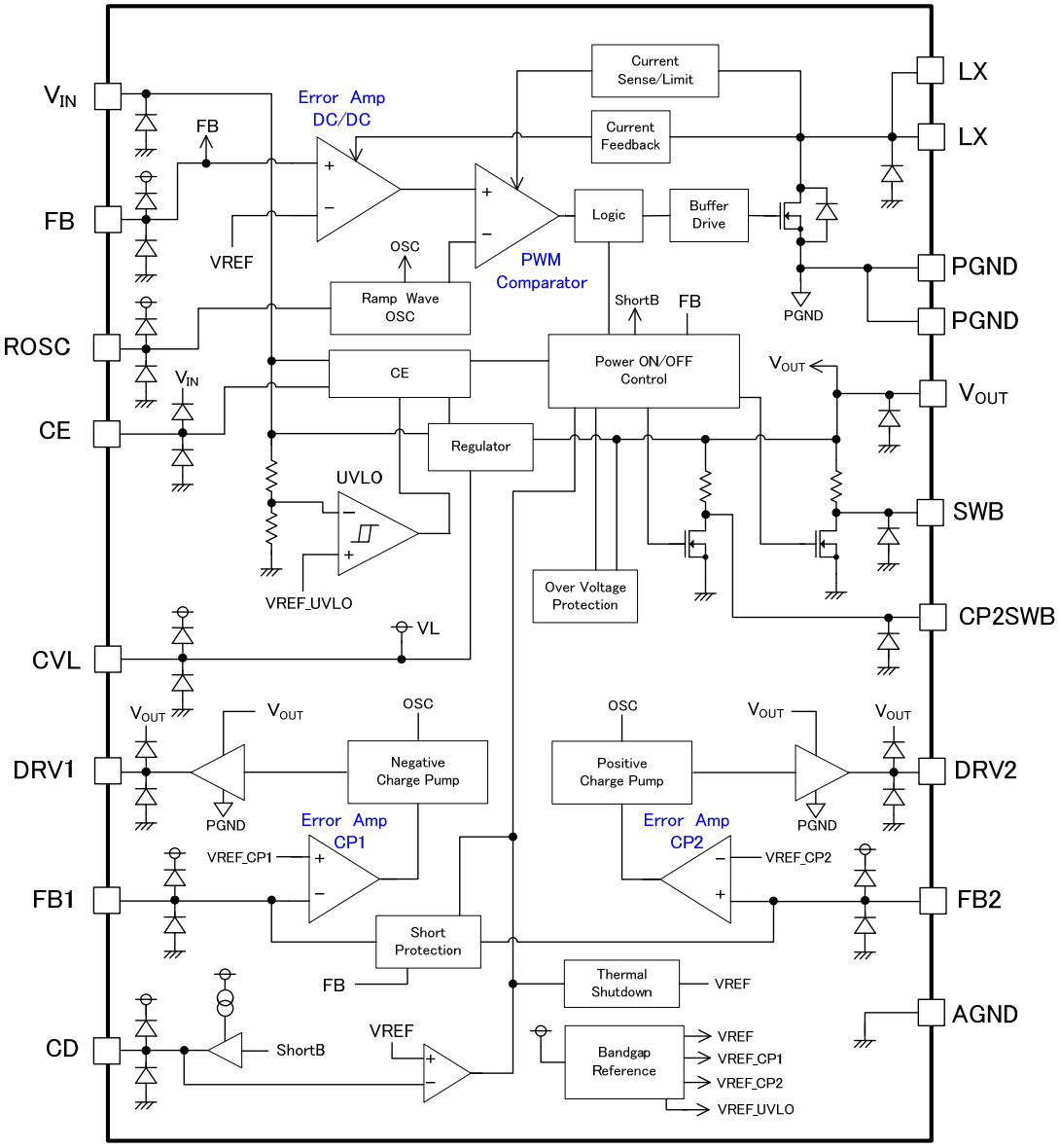
●Ordering Information

XC9516①②③④⑤⑥-⑦ (*1) ⇒ XC9516A21AZR-G

DESIGNATOR	ITEM	SYMBOL	DESCRIPTON
①	UVLO Detect Voltage	A	Detect Voltage: 1.87V, Hysteresis Width 0.44V
②③	Over Voltage Limit	21	Over Voltage Detect Voltage: 21V
④	Over Current Limit	A	Over Current Detect Voltage: 1.3A
⑤⑥-⑦ (*1)	Package (Order Unit)	ZR-G	QFN-20 (1,000/Reel) (*2)

(*1) The "-G" suffix denotes Halogen and Antimony free as well as being fully RoHS compliant.
(*2) The XC9516 reels are shipped in a moisture-proof packing.

■BLOCK DIAGRAM



PGND and AGND are externally connected to the same potential.

■ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATINGS	UNITS
V_{IN} Voltage	V_{IN}	-0.3～6.0	V
CE Pin Voltage	V_{CE}	-0.3～V_{IN}+0.3 or 6.0 (*1)	V
FB Pin Voltage	V_{FB}	-0.3～V_{CVL}+0.3 or 6.0 (*2)	V
FB1 Pin Voltage	V_{FB1}	-0.3～V_{CVL}+0.3 or 6.0 (*2)	V
FB2 Pin Voltage	V_{FB2}	-0.3～V_{CVL}+0.3 or 6.0 (*2)	V
ROSC Pin Voltage	V_{ROSC}	-0.3～V_{CVL}+0.3 or 6.0 (*2)	V
CD Pin Voltage	V_{CD}	-0.3～V_{CVL}+0.3 or 6.0 (*2)	V
CVL Pin Voltage	V_{VL}	-0.3～6.0	V
SWB Pin Voltage	V_{SWB}	-0.3～22	V
CP2SWB Pin Voltage	V_{CP2SWB}	-0.3～22	V
V_{OUT} Pin Voltage	V_{OUT}	-0.3～22	V
L_X Pin Voltage	V_{LX}	-0.3～22	V
DR1 Pin Voltage	V_{DRV1}	-0.3～V_{OUT}+0.3 or 22 (*3)	V
DR2 Pin Voltage	V_{DRV2}	-0.3～V_{OUT}+0.3 or 22 (*3)	V
L_X Pin Current	I_{LX}	1650	mA
Power Dissipation	Pd	300	mW
Operating Ambient Temperature	Topr	-40 ～ +85	°C
Storage Temperature	Tstg	-55 ～ +125	°C

* All voltages are described based on GND. (GND=AGND=PGND)

(*1) The maximum value should be either V_{IN}+0.3 or +6.0 in the lowest.

(*2) The maximum value should be either V_{CVL}+0.3 or +6.0 in the lowest.

(*3) The maximum value should be either V_{OUT}+0.3 or +22.0 in the lowest.

■ELECTRICAL CHARACTERISTICS

Unless otherwise stated, V_{IN}=V_{CE}=3.3V, V_{OUT}=9.0V, f_{OSC}=300kHz, Ta=25℃

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS	CIRCUIT
Power Input Voltage Range	V_{IN}		2.5	-	5.5	V	-
Input Voltage Rise Time	t_{VIN}	V_{IN}=V_{CE}=0.2V→2.5V (*1)	-	-	15	ms	⑳
Supply Current	I_{DD1}	V_{FB}=V_{FB2}=0.8V, V_{FB1}=1.2V, V_{CD}=0V	0.8	2.0	4.0	μA	①
Stand-by Current	I_{STB}	V_{CE}=0V	-	0.1	8.0	μA	②
Oscillation Frequency	f_{OSC}	V_{FB}=V_{FB2}=0.8V, V_{FB1}=1.2V, V_{CD}=0V, R_{OSC} Open	255	300	345	kHz	③
UVLO Detect Voltage (V_{IN} falls down)	V_{UVLO1}	V_{IN}=V_{CE}, V_{FB}=V_{FB2}=0.8V, V_{FB1}=1.2V, V_{CD}=0V	1.77	1.87	1.97	V	④
UVLO Feedback Voltage (V_{IN} rises)	V_{UVLO2}	V_{IN}=V_{CE}, V_{FB}=V_{FB2}=0.8V, V_{FB1}=1.2V, V_{CD}=0V	2.22	2.31	2.40	V	④
CE "High" Voltage	V_{CEH}	V_{FB}=V_{FB2}=0.8V, V_{FB1}=1.2V, V_{CD}=0V	1.2	-	V_{IN}	V	⑤
CE "Low" Voltage	V_{CEL}	V_{FB}=V_{FB2}=0.8V, V_{FB1}=1.2V, V_{CD}=0V	AGND	-	0.4	V	⑤
CE Input Current	I_{CE}	V_{IN}=5.5V, V_{CE}=0V or 5.5V	-0.1	-	0.1	μA	⑥
CD Pin Charge Current	I_{CD1}	V_{FB}=0.9V→0.4V, V_{FB1}= V_{FB2}=0.9V	2.6	5.5	8.4	μA	⑦
CD Pin Discharge Current	I_{CD2}	V_{FB}=V_{FB1}=V_{FB2}=0.9V, V_{CD}=0.1V	0.20	0.38	0.56	mA	⑧
CD Pin Detect Voltage	V_{CD}	V_{FB}= V_{FB1}= V_{FB2}=0V	0.95	1.0	1.05	V	⑨
CP2SWB "L" Output Voltage	V_{SWB2}	Input Current=1mA	0.55	0.65	0.80	V	⑩
SWB "L" Output Voltage	V_{SWB}	Input Current=1mA	0.26	0.33	0.40	V	⑩
CP2SWB Pull up Resistance	R_{CP2}	V_{CE}＝0V,V_{OUT}=5.5V,CP2SWB=1.0V	350	800	2500	kΩ	⑪
SWB Pull up Resistance	R_{SWB}	V_{CE}＝0V,V_{OUT}=5.5V,SWB=1.0V	350	800	2500	kΩ	⑪
Thermal Shutdown Temperature	T_{TSD}		-	150	-	°C	-
Hysteresis Width	T_{HYS}		-	20	-	°C	-
●Step-Up DC/DC Converter Block							
FB Voltage	V_{FB}	V_{FB1}=1.2V, V_{FB2}=0.8V, V_{CD}=0V	0.985	1	1.015	V	⑫
Setting Output Voltage Range	V_{OUTSET}		5.5	-	19	V	-
Maximum Duty Cycle	D_{MAX}	V_{FB}=V_{FB1}=V_{FB2}=0V, V_{CD}=0V, R_{OSC} Open	92	95	98	%	⑬
Soft-Start Time	t_{SS}		2.0	4.0	5.0	ms	⑲
L_X "N-ch" ON Resistance	R_{LXN}		100	190	400	mΩ	-
L_X Current Limit	I_{LIM}	f_{OSC}=1.0MHz	1.1	1.3	1.5	A	⑱
V_{OUT} Over Voltage Limit	V_{OVP}		19.5	21	22	V	⑰
Short Protection Voltage	V_{SHORT}	V_{FB1}=V_{FB2}=0.9V, C_D=0.1μF	0.40	0.48	0.55	V	⑮
FB Input Current	I_{FB}	V_{IN}=5.5V, V_{CE}＝0V, V_{FB}=0V, 5.5V	-0.1	-	0.1	μA	⑭
●Negative Charge Pump Block							
FB1 Voltage	V_{FB1}	V_{FB}=V_{FB2}=0.8V, V_{CD}=0V	0.985	1	1.015	V	⑫
Output Impedance 1	R_{OUT1}	V_{FB1}=1.2V, I_{DRV1}=20mA	-	15	45	Ω	⑯
Short Protection Voltage 1	V_{SHORT1}	V_{FB}=V_{FB2}=0.9V, C_D=0.1μF	1.2	2.4	2.8	V	⑮
FB1 Input Current	I_{FB1}	V_{IN}=5.5V, V_{CE}＝0V , V_{FB1}=0V, 5.5V	-0.1	-	0.1	μA	⑭
●Positive Charge Pump Block							
FB2 Voltage	V_{FB2}	V_{FB}=0.8V, V_{FB1}=1.2V, V_{CD}=0V	0.985	1.0	1.015	V	⑫
Output Impedance 2	R_{OUT2}	V_{FB2}=0.8V, I_{DRV2}=20mA	-	15	45	Ω	⑯
Short Protection Voltage 2	V_{SHORT2}	V_{FB}=V_{FB1}=0.9V, C_D=0.1μF	0.40	0.48	0.55	V	⑮
FB2 Input Current	I_{FB2}	V_{IN}=5.5V, V_{CE}＝0V , V_{FB2}=0V, 5.5V	-0.1	-	0.1	μA	⑭

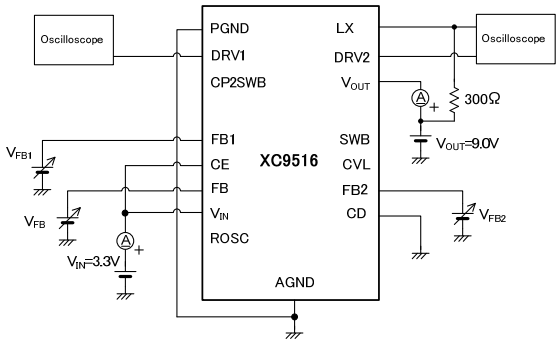
(*1)Test Condition for input voltage rise time

When used at V_{IN}=V_{CE}, input voltage should rise from 0.2V to 2.5V within 15ms.

Please also note input voltage before rise should be less than 0.2V. Please see test circuit 20 for test condition, and for the detail of recommended input wave form, please see NOTES ON USE.

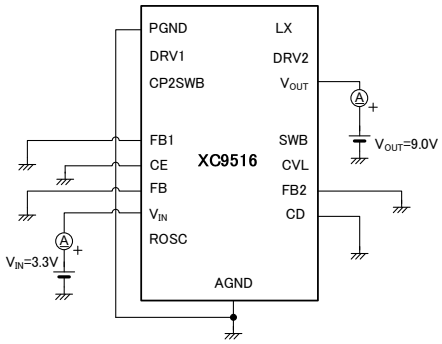
■TEST CIRCUITS

<Circuit1 Supply Current>



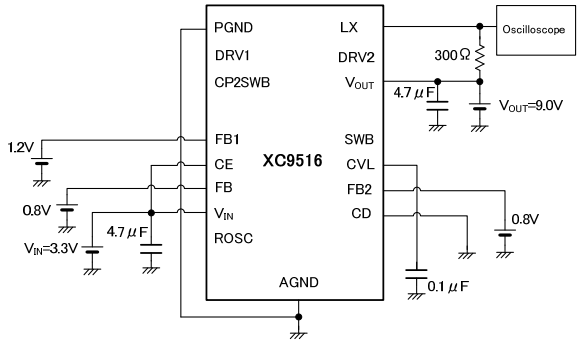
①V_{FB}=0.8V→1.2V→0.8V L_X oscillation is checked
②V_{FB1}=1.2V→0.8V→1.2V DRV1 Oscillation is checked.
③V_{FB2}=0.8V→1.2V
→0.8V DRV2 Oscillation is checked.
After ①~③, supply current is measured at both V_{IN} and V_{OUT}.

<Circuit2 Stand-by Current>



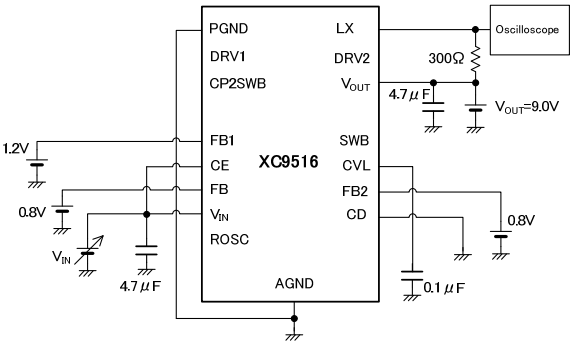
V_{CE}=0V, supply current is measured at both V_{IN} and V_{OUT}.

<Circuit3 Oscillation Frequency>



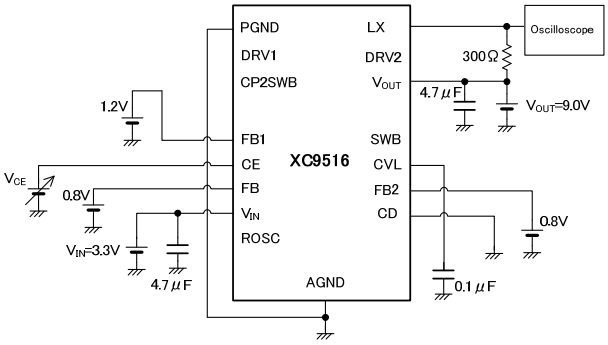
L_X Oscillation period is measured.

<Circuit4 UVLO Detect/Release Voltage>



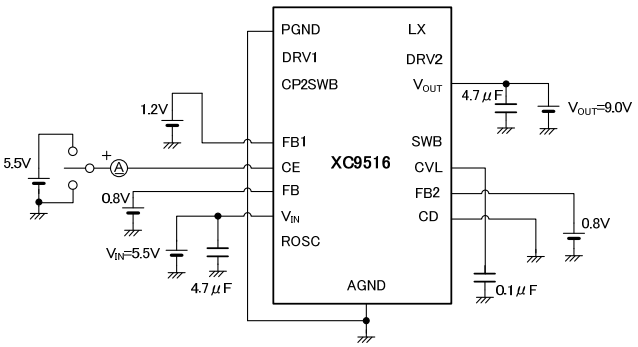
UVLO Detect Voltage Measurement: V_{IN} is decreased (2.5V→1.5V), V_{IN} is measured when L_X oscillation stopped.
UVLO Release Voltage Measurement: V_{IN} is increased (1.5V→2.5V) when L_X oscillation started,

<Circuit5 CE H/L Voltage>



CE H Voltage Measurement: V_{CE} is increased(0.4V→1.2V), V_{CE} is measured when L_X oscillation started.
CE L Voltage Measurement: V_{CE} is decreased(1.2V→0.4V), V_{CE} is measured when L_X oscillation stopped.

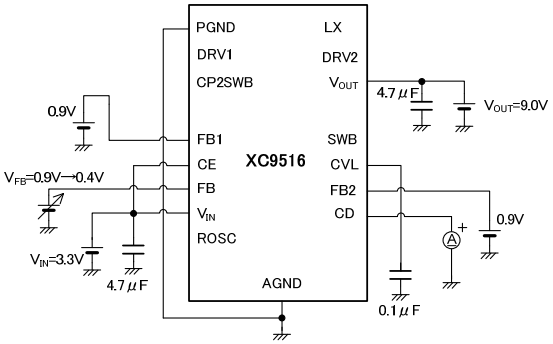
<Circuit6 CE H/L Input Current>



CE H Input Current: Current is measured when CE pin Voltage is 5.5V.
CE L Input Current: Current is measured when CE pin Voltage is 0V.

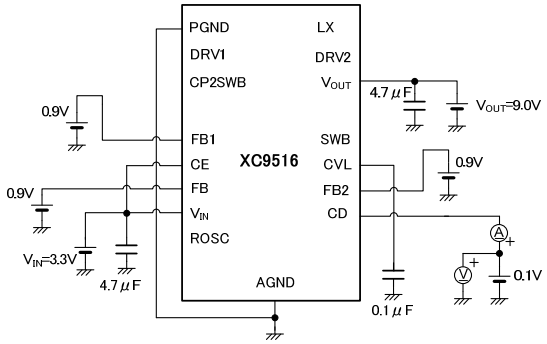
■TEST CIRCUITS (Continued)

< Circuit7 C_D pin Charge Current>



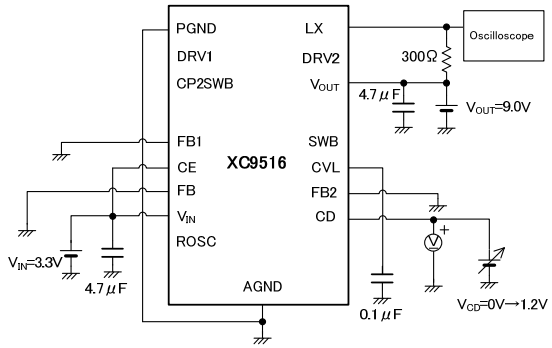
After V_{FB}=0.9V→0.4V, CD pin output current is measured.

< Circuit8 C_D pin Discharge Current>



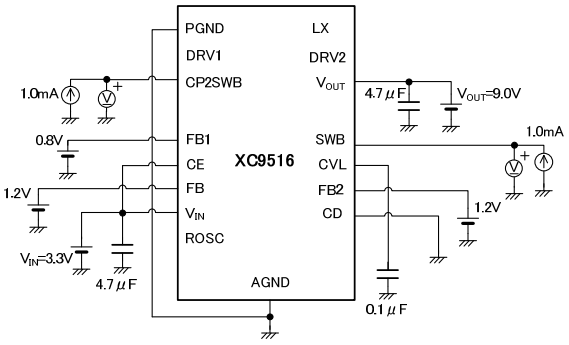
Input current is measured when C_D pin Voltage is 0.1V.

<Circuit9 C_D pin Detect Voltage>



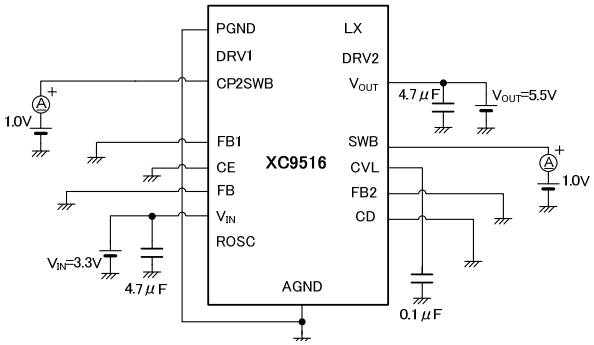
V_{CD}=0.1V→0.2 V_{CD} is measured when L_X oscillation stopped.

<Circuit10 CP2SWB/SWB L Output Voltage>



CP2SWB L Output Voltage: Voltage is measured when 1.0mA is flow in CP2SWB pin.
SWB L Output Voltage Voltage is measured when 1.0mA is flow in SWB pin.

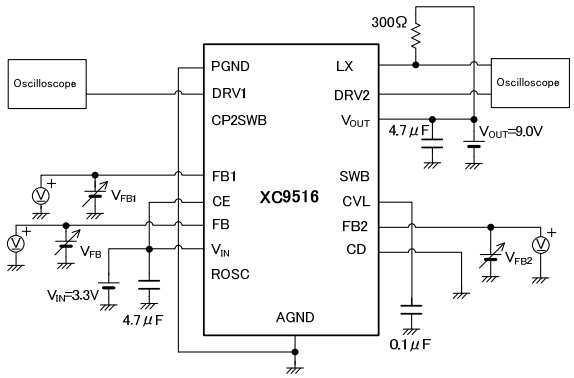
<Circuit11 CP2SWB/SWB pins Pull-up Resistance>



CP2SWB Pull-up Resistance Measurement: Output current is measured when CP2SWB pin is 1.0V.R=(5.5-1.0)/I
CP2SWB and SWB pins are internally pulled-up to V_{OUT}
SWB Pull-up Resistance Measurement: Output Current is measured when SWB pin voltage is 1.0V.R=(5.5-1.0)/I
*CP2SWB and SWB pins are internally pulled-up to V_{OUT}

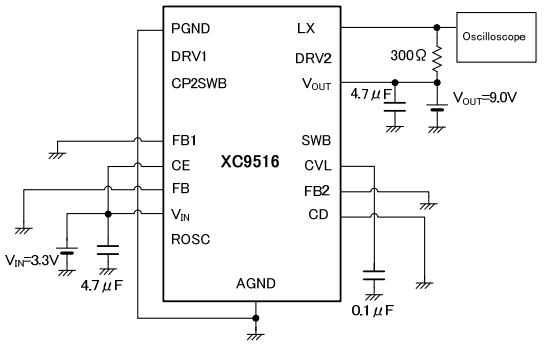
■TEST CIRCUITS (Continued)

< Circuit12 FB/FB1/FB2 Voltage Test>



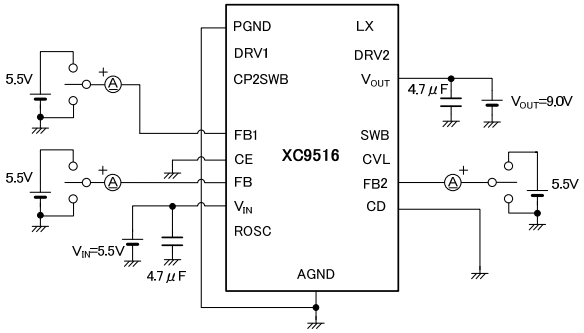
FB Voltage Measurement: V_{FB}=1.1V→0.9V, V_{FB} is measured when L_X oscillation started.
FB1 Voltage Measurement: V_{FB1}=0.9V→1.1V, V_{FB1} is measured when DRV1 oscillation started.
FB2 Voltage Measurement: V_{FB2}=1.1V→0.9V, V_{FB2} is measured when DRV2 oscillation started.

< Circuit13 Maximum Duty Cycle>



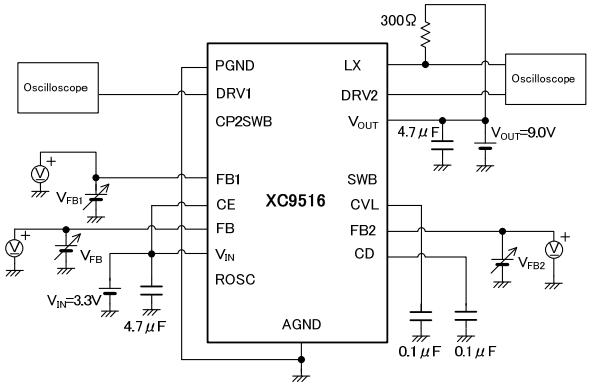
Duty cycle of L_X oscillation is measured.

< Circuit14 FB/FB1/FB2 H/L Input Current>



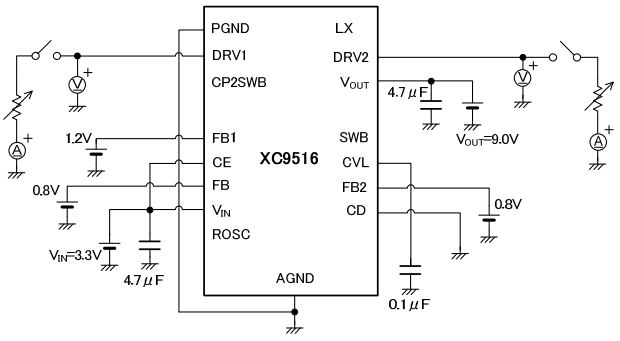
FB Input Current Measurement: Input Current is measured when FB Voltage is 5.5V/0V.
FB1 Input Current Measurement: Input Current is measured when FB1 Voltage is 5.5V/0V.
FB2 Input Current Measurement: Input Current is measured when FB2 Voltage is 5.5V/0V.

< Circuit15 FB/FB1/FB2 Short Circuit Protection>



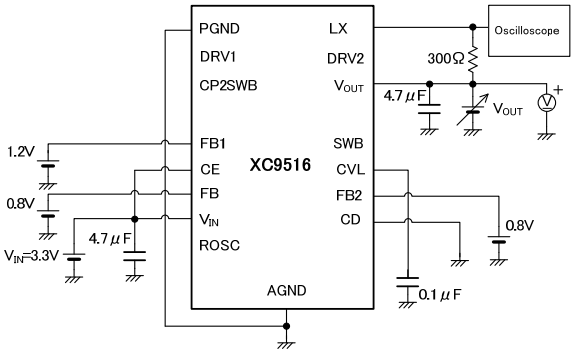
FB Short Protection Measurement: V_{FB}=0.9V→0.4V, V_{FB} is measured when V_{FB} oscillation stopped.
FB1 Short Protection Measurement: V_{FB1}=1.2V→2.8V, V_{FB1} is measured when DRV1 oscillation stopped.
FB2 Short Protection Measurement: V_{FB2}=0.9V→0.4V, V_{FB2} is measured when DRV2 oscillation stopped.

< Circuit16 Output Impedance 1/2>



Output Impedance1: A load current of 20mA is applied to DRV1,
DRV1 voltage is measured when a load is applied or not applied R=V/0.02.
Output Impedance2: A load current of 20mA is applied to DRV2,
DRV2 voltage is measured when a load is applied or not applied R=V/0.02.

< Circuit17 V_{OUT} Over Voltage Limit Measurement>

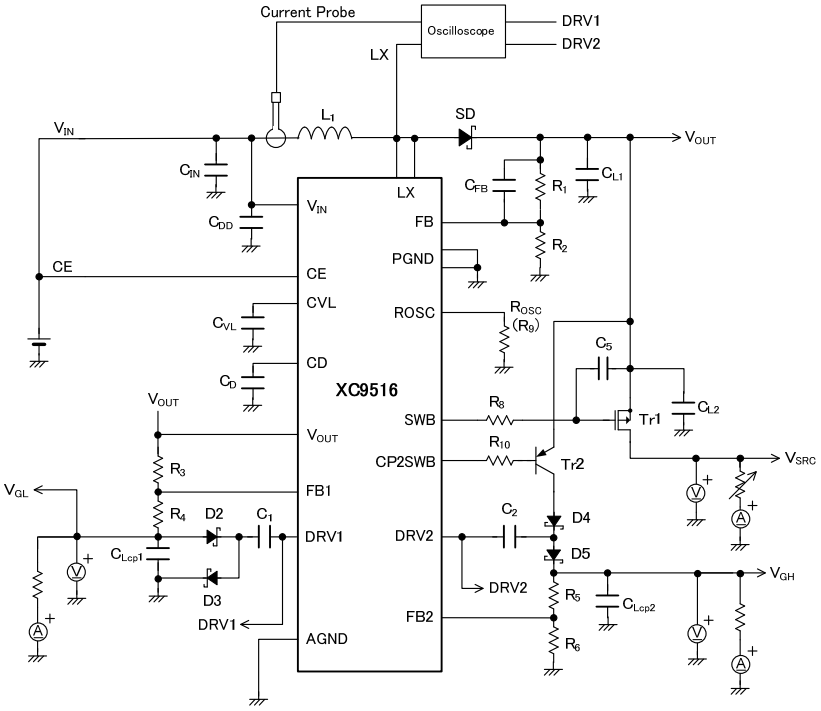


V_{OUT}=18V→22V, V_{OUT} is measured when L_x oscillation stopped.

■TEST CIRCUITS (Continued)

< Circuit18 L_X Current Limit>

・A load current (Variable Resistor) is connected to V_{SRC}.
Coil peak current at V_{IN}-L_1 is monitored by the current probe. A coil peak current is measured.



< Circuit18 L_X External Components List>

NAME	MODEL NAME	CHARACTERISTIC	MANUFACTURER
L_1	LTF5022T-4R7N2R0	Coil, 4.7μH	TDK
SD	XBS204S17	Schottky diode, 2A/40V	TOREX
D2-5	XBS104S13	Schottky diode, 1A/40V	TOREX
Tr1	XP152A11E5MR	Pch MOSFET	TOREX
Tr2	CPH3109	PNP transistor	SANYO
C_{IN}	LMK212BJ475KG	ceramic condenser, 4.7μF/10V	TAIYO YUDEN
C_D,C_{VL}	TMK107BJ104KA	ceramic condenser, 0.1μF/25V	TAIYO YUDEN
C_{DD}	TMK107BJ105KA	ceramic condenser, 1μF/25V	TAIYO YUDEN
C_{L1},C_{L2}	C3216X5R1E475M	ceramic condenser, 4.7μF/25V	TDK
C_{Lcp1},C_{Lcp2}	TMK107BJ105KA	ceramic condenser, 1μF/25V	TAIYO YUDEN
C_{FB}	C1608JB1H220J	ceramic condenser, 22pF/50V	TDK
C_1,C_2	C1608JB1H103K	ceramic condenser, 0.01μF/50V	TDK
R_1	RMC1/16K824FTP	chip resistance, 820kΩ	KAMAYA
R_2	RMC1/16K104FTP	chip resistance, 100kΩ	KAMAYA
R_3	RMC1/16K394FTP	chip resistance, 390kΩ	KAMAYA
R_4	RMC1/16K304FTP	chip resistance, 300kΩ	KAMAYA
R_5	RMC1/16K824FTP	chip resistance, 820kΩ	KAMAYA
R_6	RMC1/16K753FTP	chip resistance, 75kΩ	KAMAYA
C_5	C1608JB1H103K	ceramic condenser, 0.01μF/50V	TDK
R_8	RMC1/16K304FTP	chip resistance, 300kΩ	KAMAYA
R_9	RMC1/16K134FTP	chip resistance, 130kΩ	KAMAYA
R_{10}	RMC1/16K513FTP	chip resistance, 51kΩ	KAMAYA

< Setting values when the above parts are used>

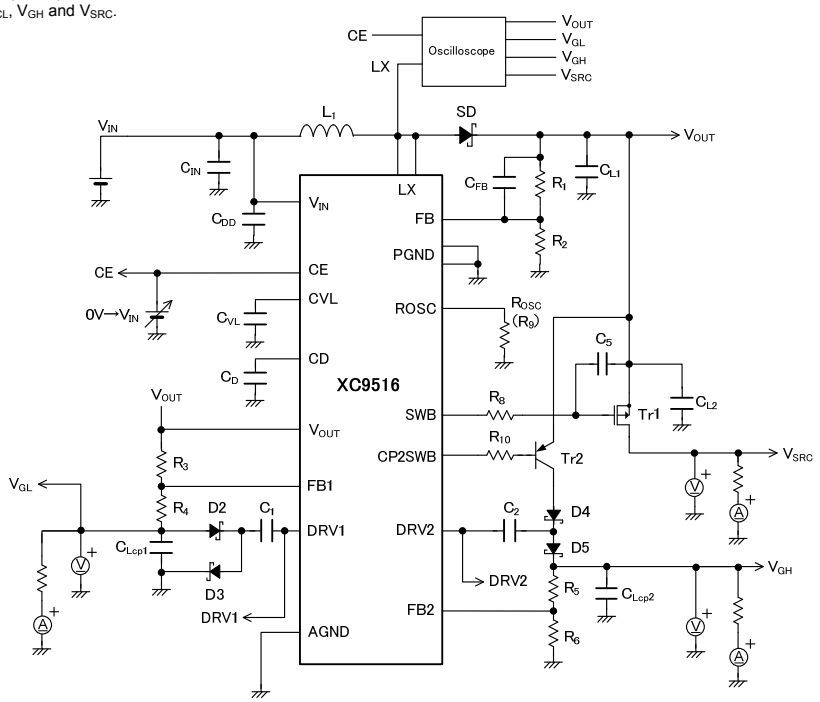
V_{OUT}=V_{SRC}=9.2V
V_{GL}=-5.3V
V_{GH}=12.0V
f_{OSC}=1.0MHz

■TEST CIRCUITS (Continued)

< Circuit19 Soft start/Start-up Sequence>

・Soft start Measurement
CE voltage is triggered on rising edge (0V→V_{IN}).
L_X oscillation start from 1.0V≦V_{CE}.
V_{OUT} rising time is measured.

・Start-up Sequence Measurement
Trigger on CE start-up. Sequence is checked in the order of V_{OUT}, V_{CL}, V_{GH} and V_{SRC}.



< Circuit19 L_X External Components List>

NAME	MODEL NAME	CHARACTERISTIC	MANUFACTURER
L_1	LTF5022T-4R7N2R0	Coil, 4.7μH	TDK
SD	XBS204S17	Schottky diode, 2A/40V	TOREX
D2-5	XBS104S13	Schottky diode, 1A/40V	TOREX
Tr1	XP152A11E5MR	Pch MOSFET	TOREX
Tr2	CPH3109	PNP transistor	SANYO
C_{IN}	LMK212BJ475KG	ceramic condenser, 4.7μF/10V	TAIYO YUDEN
C_D,C_{VL}	TMK107BJ104KA	ceramic condenser, 0.1μF/25V	TAIYO YUDEN
C_{DD}	TMK107BJ105KA	ceramic condenser, 1μF/25V	TAIYO YUDEN
C_{L1},C_{L2}	C3216X5R1E475M	ceramic condenser, 4.7μF/25V	TDK
C_{Lcp1},C_{Lcp2}	TMK107BJ105KA	ceramic condenser, 1μF/25V	TAIYO YUDEN
C_{FB}	C1608JB1H220J	ceramic condenser, 22pF/50V	TDK
C_1,C_2	C1608JB1H103K	ceramic condenser, 0.01μF/50V	TDK
R_1	RMC1/16K824FTP	chip resistance, 820kΩ	KAMAYA
R_2	RMC1/16K104FTP	chip resistance, 100kΩ	KAMAYA
R_3	RMC1/16K394FTP	chip resistance, 390kΩ	KAMAYA
R_4	RMC1/16K304FTP	chip resistance, 300kΩ	KAMAYA
R_5	RMC1/16K824FTP	chip resistance, 820kΩ	KAMAYA
R_6	RMC1/16K753FTP	chip resistance, 75kΩ	KAMAYA
C_5	C1608JB1H103K	ceramic condenser, 0.01μF/50V	TDK
R_8	RMC1/16K304FTP	chip resistance, 300kΩ	KAMAYA
R_9	RMC1/16K134FTP	chip resistance, 130kΩ	KAMAYA
R_{10}	RMC1/16K513FTP	chip resistance, 51kΩ	KAMAYA

< Setting values when the above parts are used>

V_{OUT}=V_{SRC}=9.2V
V_{GL}=-5.3V
V_{GH}=12.0V
f_{OSC}=1.0MHz

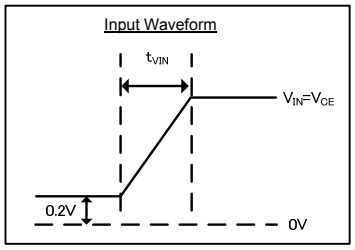
■TEST CIRCUITS (Continued)

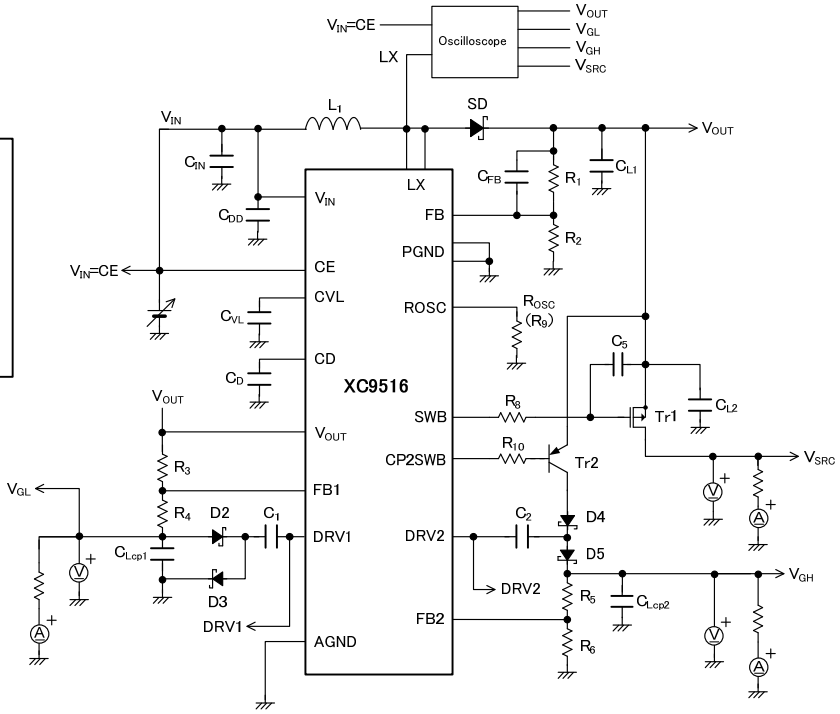
< Circuit20 Input Voltage Start-up Time>

・Input Voltage Start-up Time

- V_{SRC} is measured after rising V_{IN} and V_{CE} within less than 15ms.
  $V_{IN}=V_{CE}=0.2V \rightarrow 2.5V$, $t_{VIN} \leqq 15ms$

・Recommended Input Waveform
Start-up with $V_{IN}=V_{CE} \leqq 0.2V$
Start-up time $t_{VIN} \leqq 15ms$





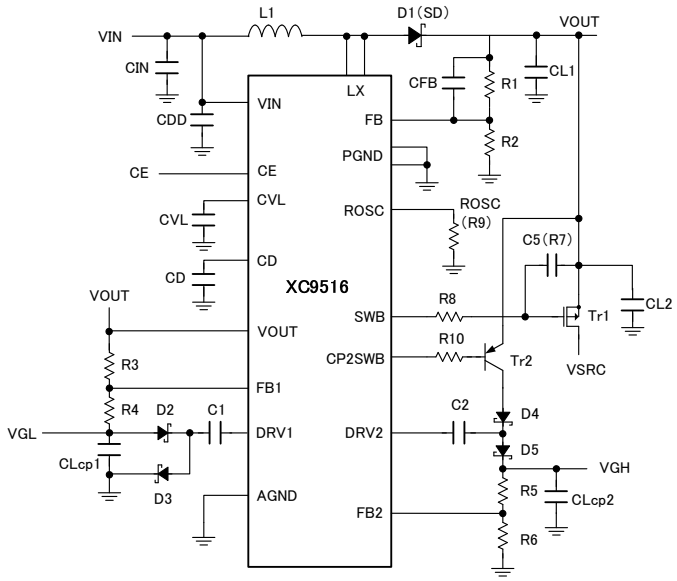
< Circuit20 L_X External Components List>

NAME	MODEL NAME	CHARACTERISTIC	MANUFACTURER
L_1	LTF5022T-4R7N2R0	Coil, 4.7μH	TDK
SD	XBS204S17	Schottky diode, 2A/40V	TOREX
D2-5	XBS104S13	Schottky diode, 1A/40V	TOREX
Tr1	XP152A11E5MR	Pch MOSFET	TOREX
Tr2	CPH3109	PNP transistor	SANYO
C_{IN}	LMK212BJ475KG	ceramic condenser, 4.7μF/10V	TAIYO YUDEN
C_D,C_{VL}	TMK107BJ104KA	ceramic condenser, 0.1μF/25V	TAIYO YUDEN
C_{DD}	TMK107BJ105KA	ceramic condenser, 1μF/25V	TAIYO YUDEN
C_{L1},C_{L2}	C3216X5R1E475M	ceramic condenser, 4.7μF/25V	TDK
C_{Lcp1},C_{Lcp2}	TMK107BJ105KA	ceramic condenser, 1μF/25V	TAIYO YUDEN
C_{FB}	C1608JB1H220J	ceramic condenser, 22pF/50V	TDK
C_1,C_2	C1608JB1H103K	ceramic condenser, 0.01μF/50V	TDK
R_1	RMC1/16K824FTP	chip resistance, 820kΩ	KAMAYA
R_2	RMC1/16K104FTP	chip resistance, 100kΩ	KAMAYA
R_3	RMC1/16K394FTP	chip resistance, 390kΩ	KAMAYA
R_4	RMC1/16K304FTP	chip resistance, 300kΩ	KAMAYA
R_5	RMC1/16K824FTP	chip resistance, 820kΩ	KAMAYA
R_6	RMC1/16K753FTP	chip resistance, 75kΩ	KAMAYA
C_5	C1608JB1H103K	ceramic condenser, 0.01μF/50V	TDK
R_8	RMC1/16K304FTP	chip resistance, 300kΩ	KAMAYA
R_9	RMC1/16K134FTP	chip resistance, 130kΩ	KAMAYA
R_{10}	RMC1/16K513FTP	chip resistance, 51kΩ	KAMAYA

< Setting values when the above parts are used>
$V_{OUT}=V_{SRC}=9.2V$
$V_{GL}=-5.3V$
$V_{GH}=12.0V$
$f_{OSC}=1.0MHz$

■OPERATIONAL EXPLANATION

XC9516 series includes following blocks which are a reference voltage source, an oscillation circuit connecting to an external R_{OSC} register, a UVLO circuit to prevent malfunction in low voltage operation, internal power supply regulator connecting external C_{VL} capacitor, a step-up DC/DC converter, step-up charge pump and inverting charge pump, a short circuit protection circuit, an over current sensing circuit, an over voltage sensing circuit and a thermal shutdown circuit.



The step-up DC/DC converter consists of a ramp wave circuit created from the above mentioned oscillation circuit, an error amplifier to compare feedback voltage through external resistor network from V_{OUT} output voltage and internal reference voltage, a PWM comparator to decide duty cycle by comparing ramp wave form created by the above mentioned ramp wave circuit and error amplifier output, a phase compensation circuit and current feedback circuit for output voltage stabilization, a N-channel MOS driver transistor to provide duty cycle on-time from L_X pin, a current limit circuit to limit the current to flow the N-channel MOS driver transistor, a over-voltage protection circuit operated at 1.3 typical to protect the devices connecting to the V_{OUT} output voltage pin.

A multi-loop feedback control by feedback voltage and N-channel MOS driver transistor provides stable output voltage operation so that low ESR ceramic capacitor can be used.

The inverting voltage charge pump consists of an error amplifier to compare internal voltage reference and the feedback voltage thorough external resistor network from V_{OUT} output voltage, output impedance control circuit to adjust output impedance by output level of the error amplifier, driver circuit for charge pump operation.

The step-up charge pump consists of an error amplifier to compare internal voltage reference and the feedback voltage thorough external resistor network from V_{OUT} output voltage, output impedance control circuit to adjust output impedance by output level of the error amplifier, driver circuit for charge pump operation.

<Reference Voltage Source>

The reference voltage source provides the reference voltage to ensure stable output voltage of the IC.

<Oscillation Circuit >

The oscillation circuit determines switching frequency. The frequency can be changed by external resistance R_{OSC} in a range of 300 kHz to 1.2MHz. When R_{OSC} pin is left open, the frequency is fixed at 300kHz.

When the frequency is low, efficiency is high at light load. When the frequency is high, “L” value of coil will be low and makes space saving.

The oscillation frequency is calculated by the following formula (Equation 1).

$$R_{OSC} = 95 \times 10^9 / (f_{OCS} - 300 \times 10^3) \cdot \cdot \cdot \text{(Equation 1)}$$

where f_{OSC} denotes a setting frequency.

< Ramp Wave Circuit >

This circuit is used to produce ramp waveforms needed for PWM operation.

< Error Amplifier for DC/DC>

The error amplifier is designed to monitor output voltage. The error amplifier compares the reference voltage with the feedback voltage through the external divider resistors. When a feedback voltage is lower than the reference voltage, the output voltage of the error amplifier is increased.

■OPERATIONAL EXPLANATION (Continued)

<External Resistors for setting Output Voltages>

A setting output voltage V_{OUT} for the step-up DC/DC is calculated by the following formula (Equation 2).

$$V_{OUT} = V_{FB} \times (R1 + R2) / R2 \cdot \cdot \cdot \text{(Equation 2)}$$

V_{FB}=1.0V, R1 + R2 ＜ 1000kΩ

A setting output voltage V_{GL} for the negative charge pump is calculated by the following formula (Equation 3).

$$V_{GL} = V_{FB1} - (V_{OUT} - V_{FB1}) \times R4 / R3 \cdot \cdot \cdot \text{(Equation 3)}$$

V_{FB1}=1.0V, R3 + R4 ＜ 1000kΩ

A setting output voltage V_{GH} for the step-up charge pump is calculated by the following formula (Equation 4).

$$V_{GH} = V_{FB2} \times (R5 + R6) / R6 \cdot \cdot \cdot \text{(Equation 4)}$$

V_{FB2}=1.0V, R5 + R6 ＜ 1000kΩ

<Regulator for Internal Power Circuit >

The XC9516 series includes a regulator for internal power circuit in order to stabilize operation. Its power source is taken from V_{IN} and V_{OUT}. An external capacitor C_{VL}=0.1μF is required to stabilize this internal power supply.

<UVLO Circuit >

When the input voltage V_{IN} falls below a threshold voltage 1.87V (TYP.), all driver transistors will be forced off to prevent malfunction. When the V_{IN} voltage becomes 2.31V (TYP.) or higher, the UVLO function is released and the IC performs the soft-start function to initiate startup operation.

< Current Limit >

The current limiter monitors the current flowing through the N-channel MOS driver transistor connected to the Lx pin, and features a combination of the current limit and latch function.

①When the driver current is greater than a specific level (a peak current of inductor), the constant-current type current limit function operates to turn off the pulses from the Lx pin at any given timing.

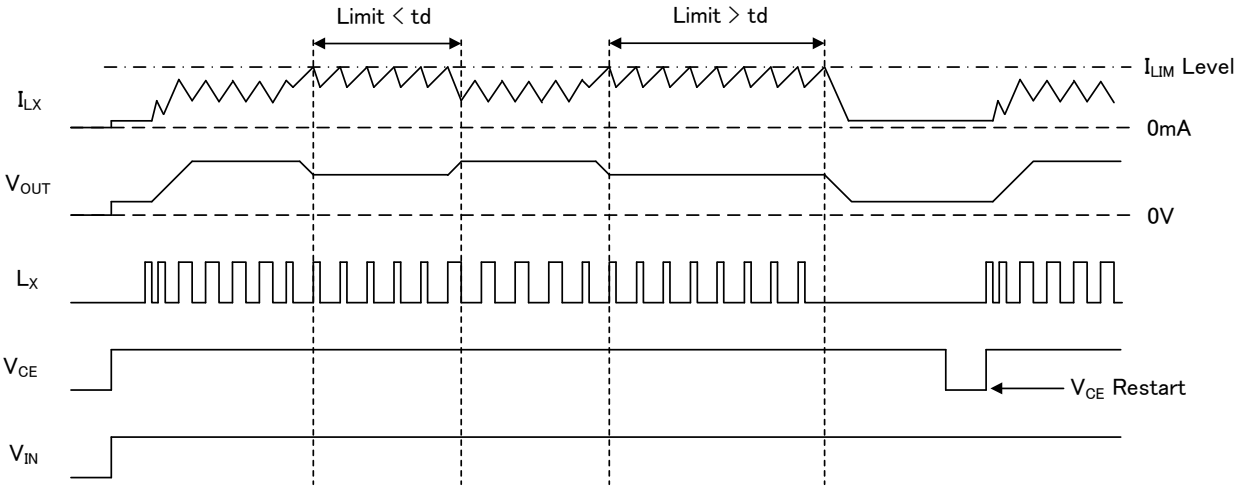
②When the driver transistor is turned off, the limiter circuit is then released from the current limit detection state.

③At the next pulse, the driver transistor is turned on. However, the transistor is immediately turned off in the case of an over-current state.

④When the over-current state is eliminated, the IC resumes its normal operation.

The IC waits for the over-current state to end by repeating the steps ①~③. During a latch delay time which was set by an external capacitor with CD pin, if the ①~③ over-current sate is repeated, all driver transistors in the step-up DC/DC converter, the step-up charge pump and the voltage inverting charge pump will be maintained to turn off. Once the IC is in suspension mode, operations can be resumed by either turning the IC off via the CE pin, or by restoring power to the V_{IN} pin.

Depending on the state of a substrate, it may result in the case where the latch delay time may become longer or the operation may not be latched. Please locate an input capacitor to the C_D pin as close as possible.



Current Limit Timing Chart

■OPERATIONAL EXPLANATION (Continued)

<Short-circuit Detection Circuit >

When either output voltage falls below the set voltage while monitoring each feedback voltage of a step-up DC/DC converter, step-up charge pump and inverting charge pump it is allowed as short-circuit so that latch delay circuit starts operation. If the output voltage goes back in the range of the set voltage within the latch delay time, the start of the latch delay circuit will be released. When output voltage is not recovered, all of the driver transistors will be turned off and latched after the latch delay time.

<Latch Delay Circuit >

Where each short-circuit detection circuit detects output voltage short-circuit or when the over-current detection circuit detects over-current of the L_X pin, All driver transistors in a step-up DC/DC converter, step-up charge pump and inverting charge pump. will be tuned off and latched after the delay time which was set by an external capacitor to the C_D pin. In order to release the latch, either turning the IC off and on via the CE pin or restoring power supply (V_{IN} pin) should be selected. A setting delay time t_D is calculated by the following formula (Equation 5).

$$C_D = t_d \times 5.5 \times 10^{-6} / 1.0 \cdots \text{(Equation 5)}$$

5.5×10^{-6} (C_D Pin Charge Current, Typical)

1.0 (C_D Pin Detect Voltage, TYP.)

<Thermal Shutdown>

For protection against heat damage of the ICs, thermal shutdown function monitors chip temperature. The thermal shutdown circuit starts operating and all of the driver transistors will be turned off when the chip's temperature reaches 150°C. When the temperature drops to 130°C or less after shutting of the current flow, the IC performs the soft start function to initiate output startup operation.

<Over-voltage Protection>

The over-voltage limit monitors the voltage of V_{OUT} pin. All of the driver transistors will be turned off when the voltage of V_{OUT} pin elevates and beyond 21V (TYP.). In order to release the latch, either turning the IC off and on via the CE pin or restoring power supply (V_{IN} pin) should be selected.

■OPERATIONAL EXPLANATION (Continued)

<Start-up Sequence>

After V_{IN} input with CE same time, the DC/DC starts to operate to set V_{OUT} voltage. After the DC/DC start-up, a negative inverting charge pump starts to operate to see V_{GL} voltage. After the negative charge pump, CP2SWB low signal output turns Tr2 on to make a positive charge pump starts to operate to see V_{GH} voltage. After V_{GH} output, SWB low signal output turn Tr1 on for V_{SRC} output. The CP2SWB and SWB pins are internally pulled up to V_{OUT}, therefore, this V_{OUT} level is kept until a low signal come out. When falling, V_{OUT}, V_{GL}, and V_{GH} outputs go off after V_{IN} and V_{CE} goes to ground. The V_{SRC} output will be turned off when the Tr2 goes off.

When Rising

①V_{IN}=V_{CE} input

②V_{OUT} Rising completed

③V_{GL} Operation started

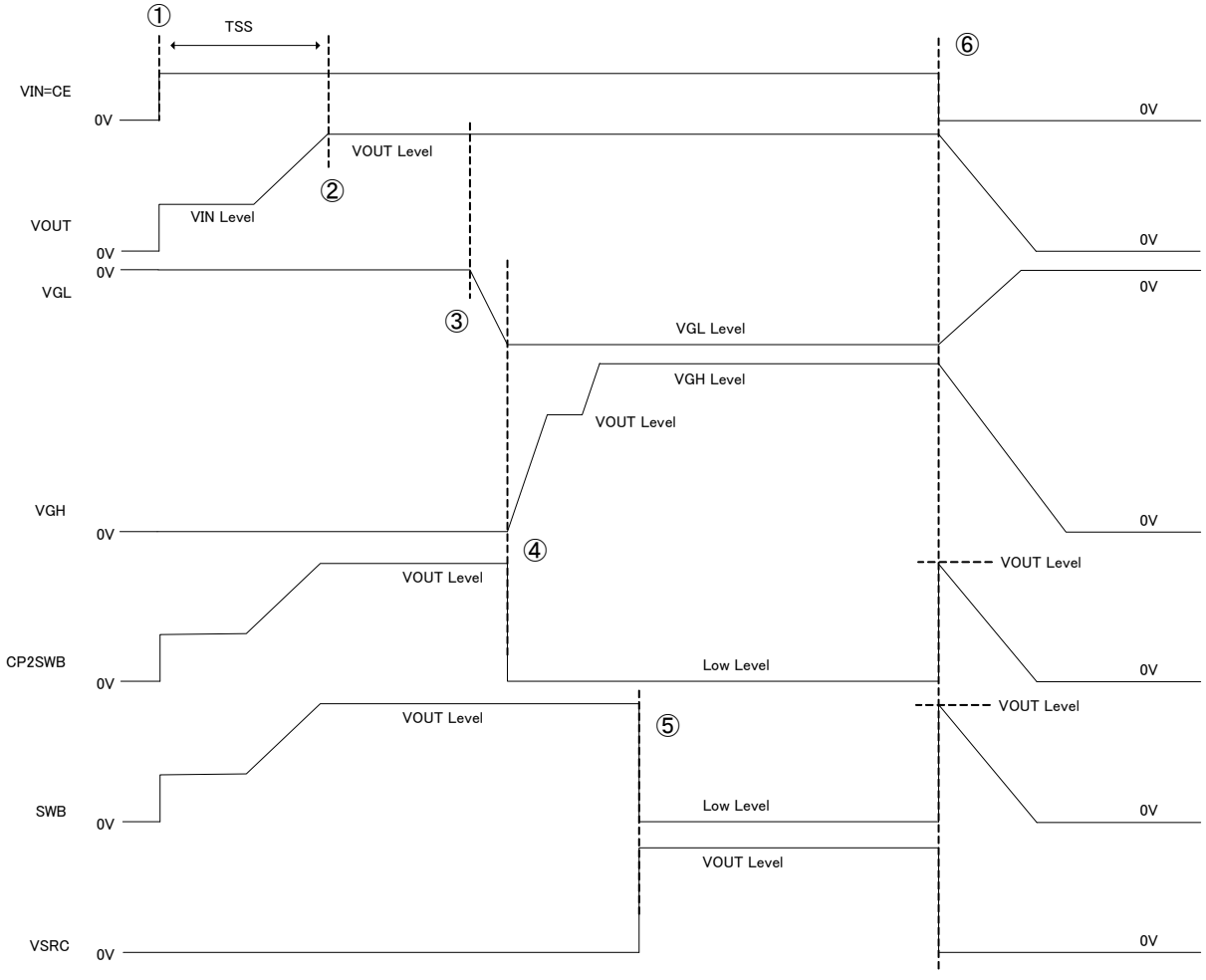
④CP2SWB Low output, V_{GH} rising started

⑤SWB Low output, V_{SRC} output

When Falling

⑥V_{IN}=V_{CE}=0V, V_{OUT}, V_{GL}, V_{GH}, V_{SRC} output is OFF

Rising/Falling Sequence



■NOTES ON USE

1. For temporary, transitional voltage drop or voltage rising phenomenon, the IC is liable to malfunction should the ratings be exceeded.

2. Switching regulators like step-up DC/DC converters may cause spike noise and/or ripple voltage. These amounts are greatly affected by peripheral components (coil inductance values, capacitor value and substrate layout of peripheral circuit). Test and inspect the actual circuits thoroughly before use.

3. An input capacitor should be placed near the IC V_{IN} pin as much as possible.

4. As for power-on, when CE pin is used with connecting to V_{IN} pin, V_{IN}-V_{CE} voltage should begin rising from below 2.0V. Rise time should be less than 15ms. (Please refer to Figure 1.)
   On the other hand, when CE pin is used independently from V_{IN} pin, CE pin voltage should be started to rise after V_{IN} pin voltage rising. (Please refer to Figure 2.)

5. GND pattern should be layouted to get a same level of voltage for AGND pin, PGND pin, and package heatsink.

6. When current over limited value (peak current) flows for a specified period, current limit circuit will turn off a built-in driver transistor (integral latch circuit). Until the circuit detects the latch delay time and turns off the build-in driver transistor, current of limited level continues to flow, so please take full care of rating of coils.

7. In case of V_{GL} voltage, V_{GH} voltage may overshoots or undershoots when power supply rise, please put speed-up capacitor (CFB1, CFB2) between FB1 pin and V_{GL}, FB2 pin and V_{GH}. (Please refer to figure 3 and 4.)

8. When load of inverting charge pump and step-up charge pump are with no load and load current of step-up DC/DC converter is large, the output of the each charge pump may become unstable by switch of step-up DC/DC converter. In case of that, please put a ferrite bead (L2) into a driver output (DRV1 pin and DRV2 pin) of the each charge pump. (Please refer to figure 4.)

9. Torex places an importance on improving our products and its reliability.
   However, by any possibility, we would request user fail-safe design and post-aging treatment on system or equipment.

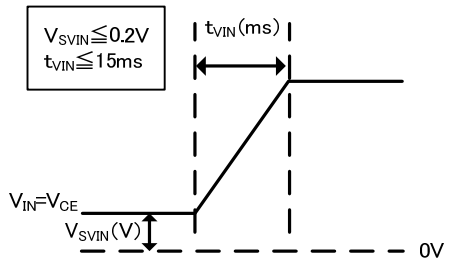


Figure 1. (Recommended for input wave form for V_{IN}=V_{CE})
Rising is recommended from less than 0.2V.
Rise time should be within 15ms.

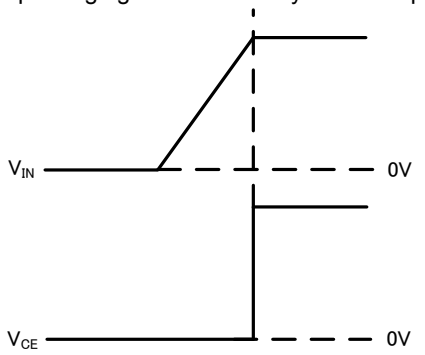


Figure 2. (Recommended for input wave form for V_{IN} pin and CE pin are input separately.)
CE should be rising after V_{IN} rising.

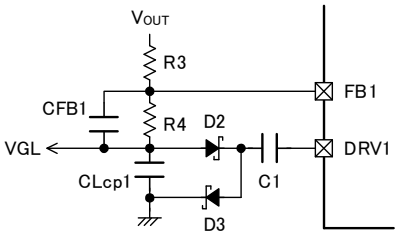


Figure 3.
Connection diagram for speed-up capacitor (CFB1)
CFB1 is connected to between FB1 pin and V_{GL}

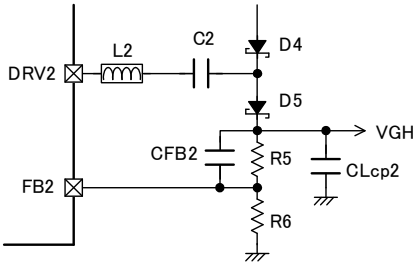
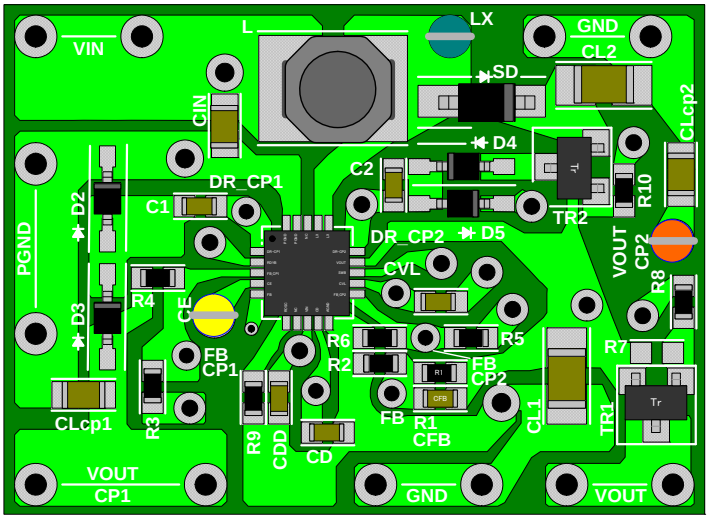


Figure 4.
Connection diagram for a ferrite bead / speed-up capacitor (CFB2)
L2 (ferrite bead) is connected to between DRV2 pin and C2.
CFB2 is connected to between FB2 pin and V_{GH}.

■NOTES ON USE (Continued)

TOP VIEW (Layout example)



*Notes for Board

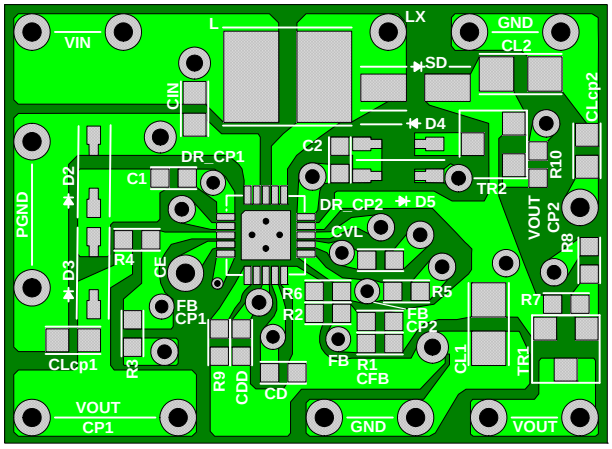
VOUTCP1=V_{GL}

VOUTCP2=V_{GH}

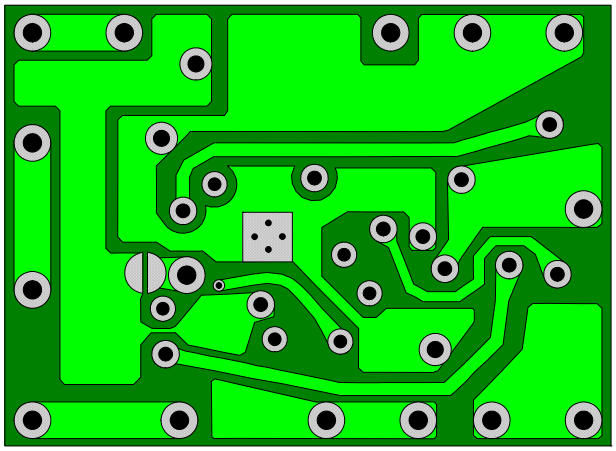
Components List

DESIGNATOR	PRODUCT	NOTE	MAKER	QTY
IC	XC9516A21AZR-G		TOREX	1
L	LTF5022T-4R7N2R0	Coil, 4.7μH	TDK	1
SD	XBS204S17	Schottky Barrie Diodes, 2A/40V	TOREX	1
D2, D3, D4,	XBS104S13	Schottky Barrie Diodes, 1A/40V	TOREX	4
Tr1	XP152A11E5MR	P-ch MOS FET	TOREX	1
Tr2	CPH3109	PNP Transistor	SANYO	1
CIN	LMK212BJ475KG	Ceramic Capacitor, 4.7μF/10V	TAIYO UDEN	1
CD, CVL	TMK107BJ104KA	Ceramic Capacitor, 0.1μF/25V	TAIYO UDEN	2
CDD	TMK107BJ105KA	Ceramic Capacitor, 1μF/25V	TAIYO UDEN	1
CL1, CL2	C3216X5R1E475M	Ceramic Capacitor, 4.7μF/25V	TDK	2
CLcp1, CLcp2	TMK107BJ105KA	Ceramic Capacitor, 1μF/25V	TAIYO UDEN	2
CFB	C1608JB1H220J	Ceramic Capacitor, 22pF/50V	TDK	1
C1, C2	C1608JB1H103K	Ceramic Capacitor, 0.01μF/50V	TDK	2
R1	RMC1/16K824FTP	Chip Resistor, 820kΩ	KAMAYA ELECTRIC	1
R2	RMC1/16K104FTP	Chip Resistor, 100kΩ	KAMAYA ELECTRIC	1
R3	RMC1/16K394FTP	Chip Resistor, 390kΩ	KAMAYA ELECTRIC	1
R4	RMC1/16K304FTP	Chip Resistor, 300kΩ	KAMAYA ELECTRIC	1
R5	RMC1/16K824FTP	Chip Resistor, 820kΩ	KAMAYA ELECTRIC	1
R6	RMC1/16K753FTP	Chip Resistor, 75kΩ	KAMAYA ELECTRIC	1
R7	C1608JB1H103K	Ceramic Capacitor, 0.01μF/50V	TDK	1
R8	RMC1/16K304FTP	Chip Resistor, 300kΩ	KAMAYA ELECTRIC	1
R9	RMC1/16K134FTP	Chip Resistor, 130kΩ	KAMAYA ELECTRIC	1
R10	RMC1/16K513FTP	Chip Resistor, 51kΩ	KAMAYA ELECTRIC	1
L2	MMZ1608S400A	Ferrite bead, 40Ω@100MHz	TDK	1

TOP VIEW

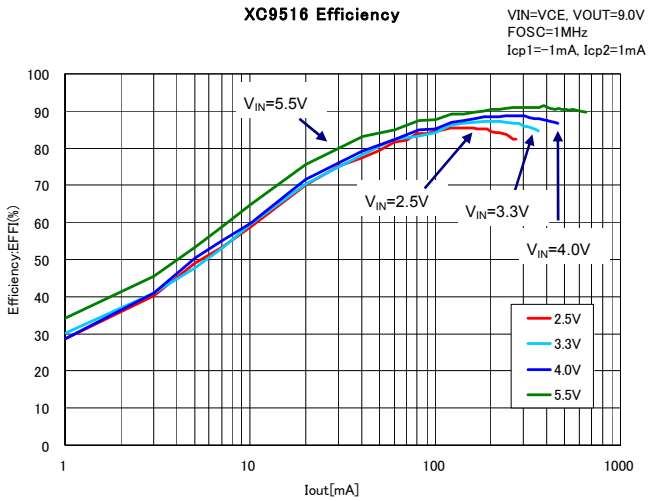


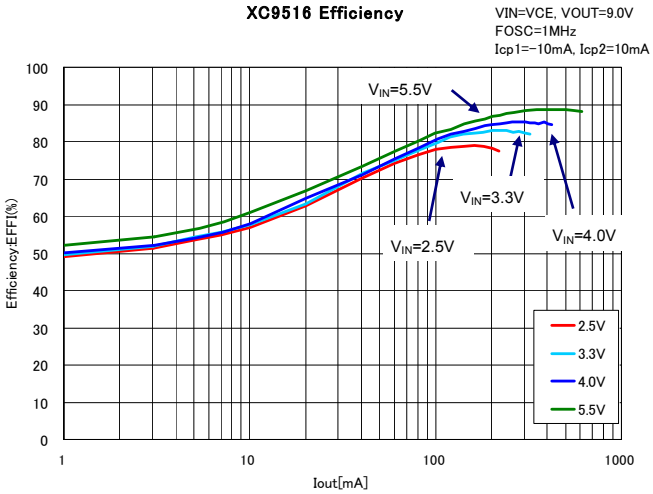
BOTTOM VIEW (Flip horizontal)



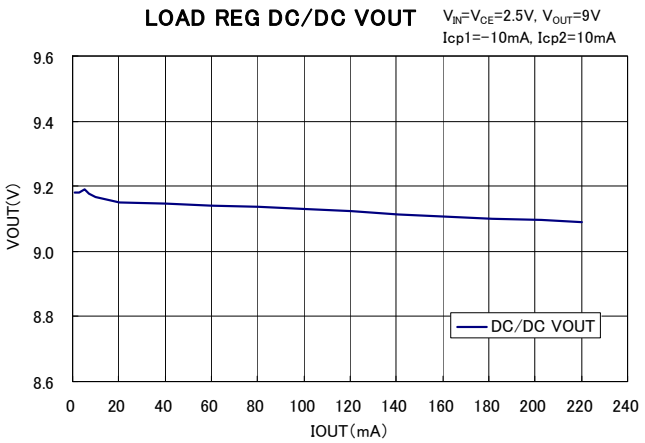
■TYPICAL PERFORMANCE CHARACTERISTICS

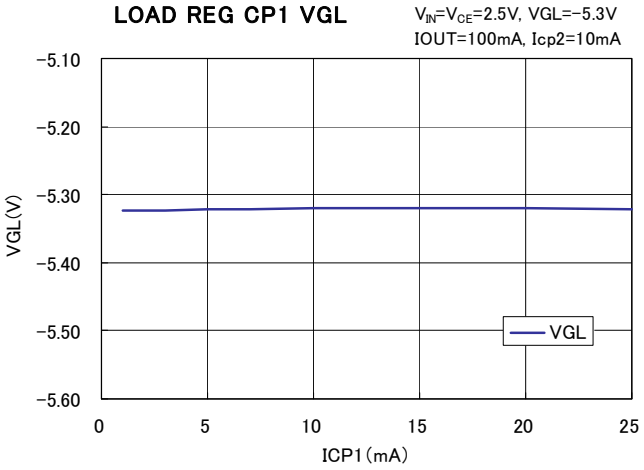
(1) Efficiency vs. Output Current

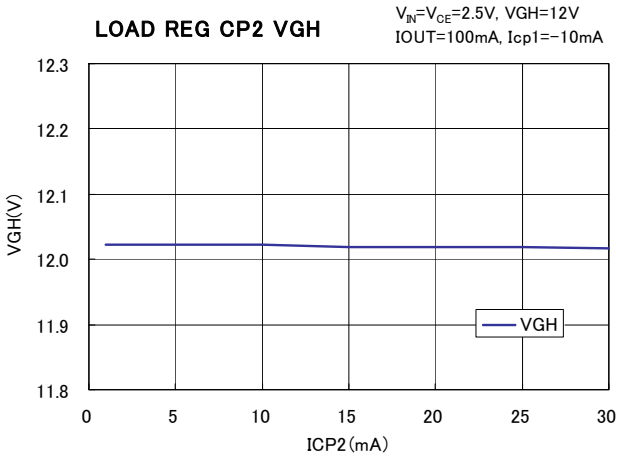




(2) Output Voltage vs. Output Current

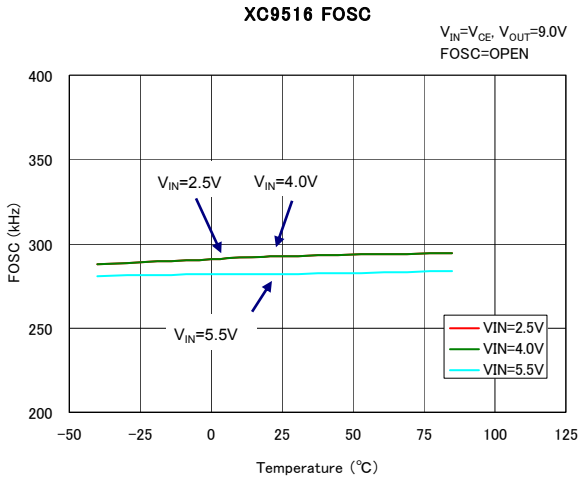




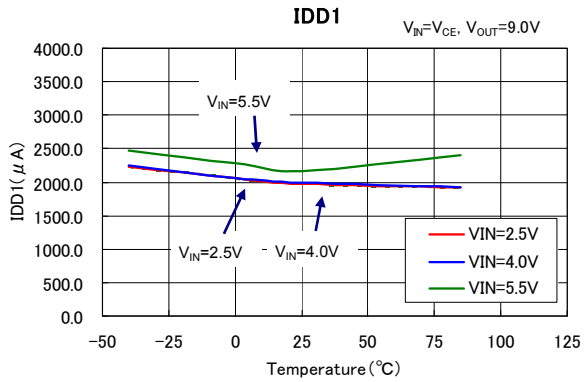


■TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

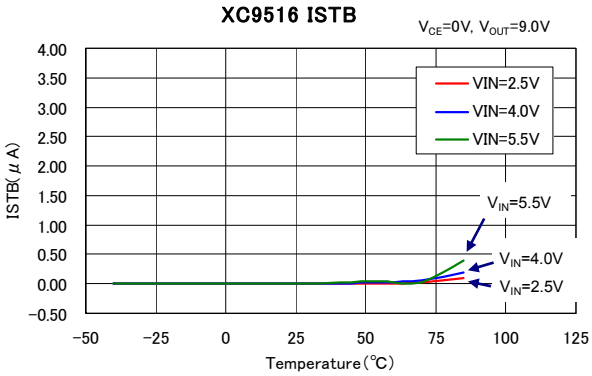
(3) Frequency vs. Ambient Temperature



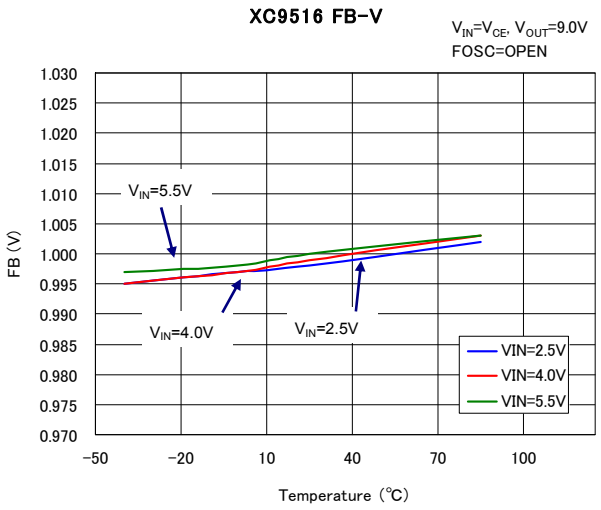
(4) Supply Current vs. Ambient Temperature



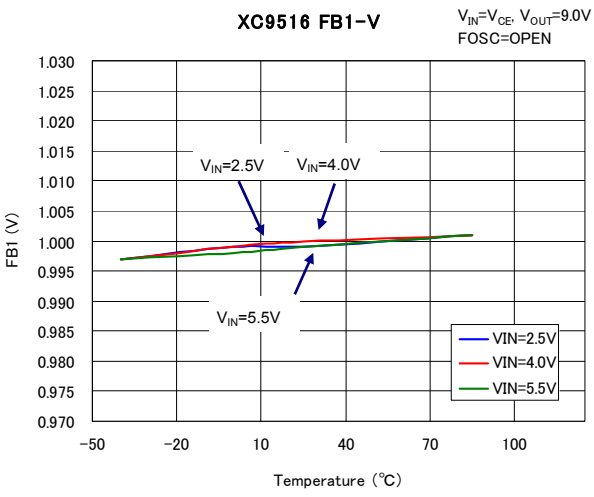
(5) Stand-by Current vs. Ambient Temperature



(6) FB Voltage vs. Ambient Temperature

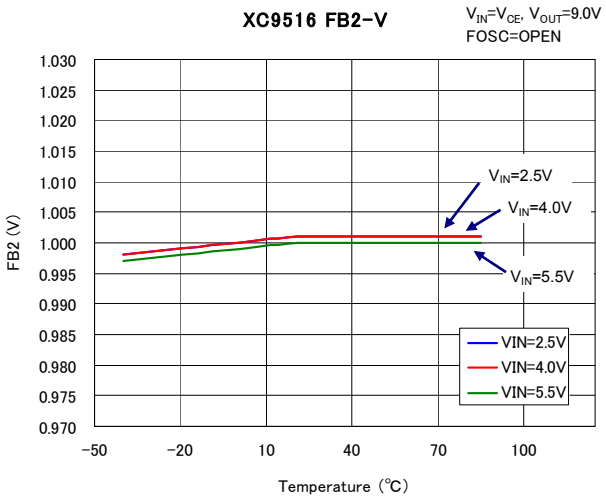


(7) FB1 Voltage vs. Ambient Temperature

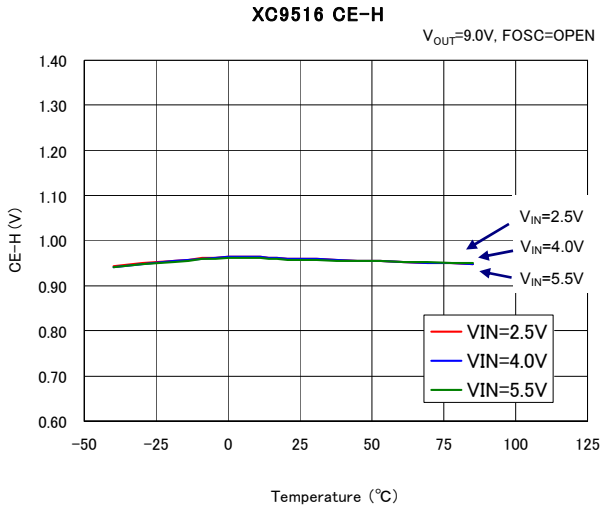


■TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

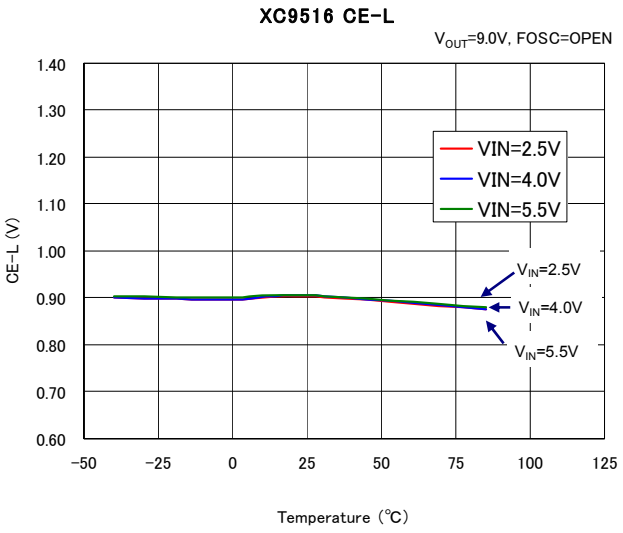
(8) FB2 Voltage vs. Ambient Temperature



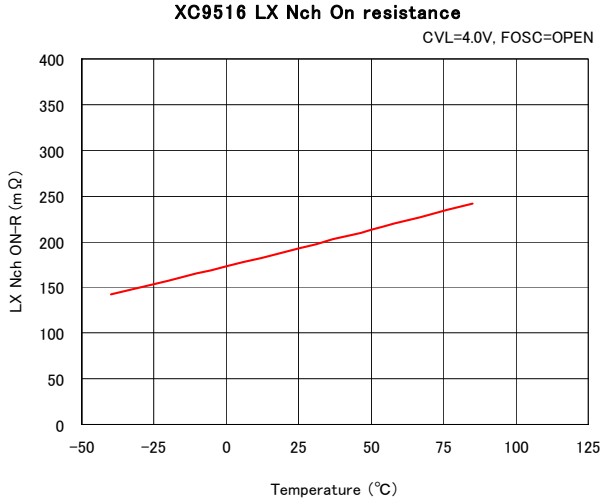
(9) CE "H" Voltage vs. Ambient Temperature



(10) CE "L" Voltage vs. Ambient Temperature

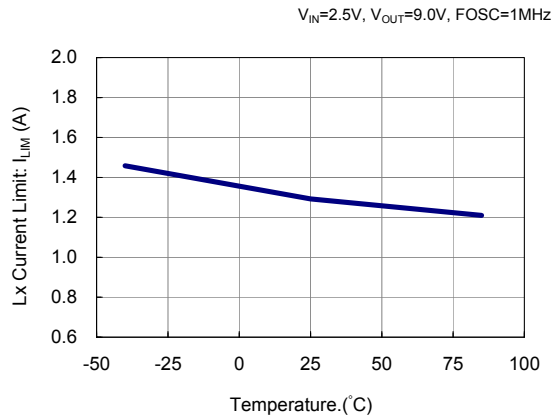


(11) LX Pin N-ch Driver ON Resistance vs. Ambient Temperature

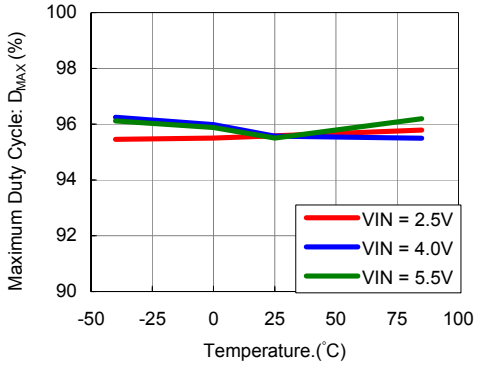


■TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

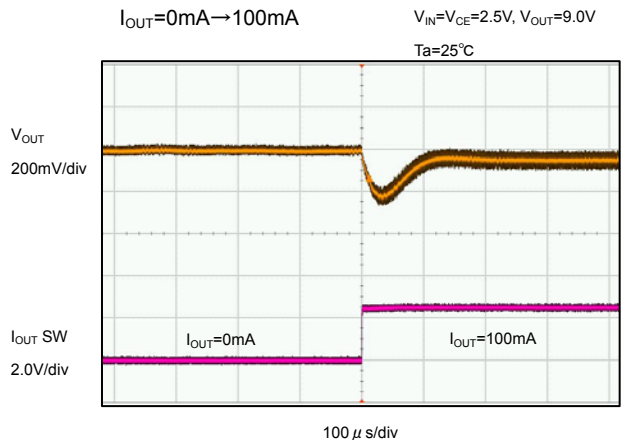
(12) LX Current Limit vs. Ambient Temperature

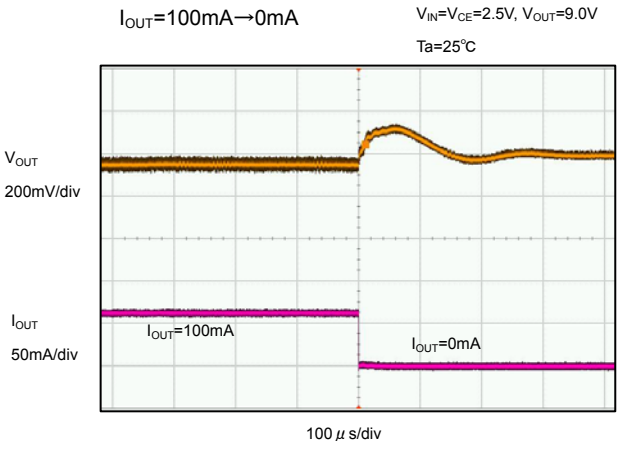


(13) Maximum Duty Cycle vs. Ambient Temperature

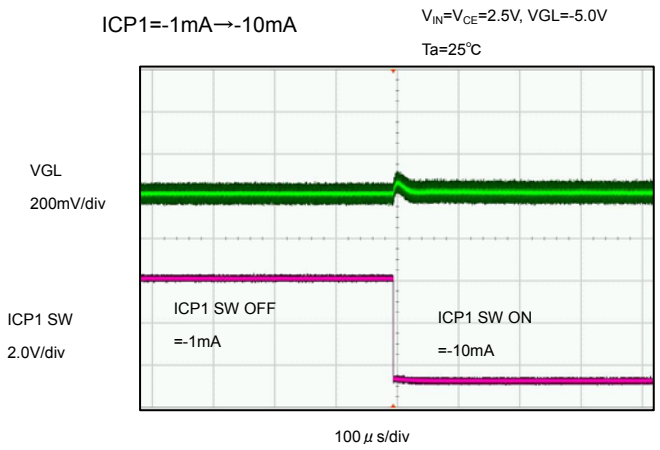


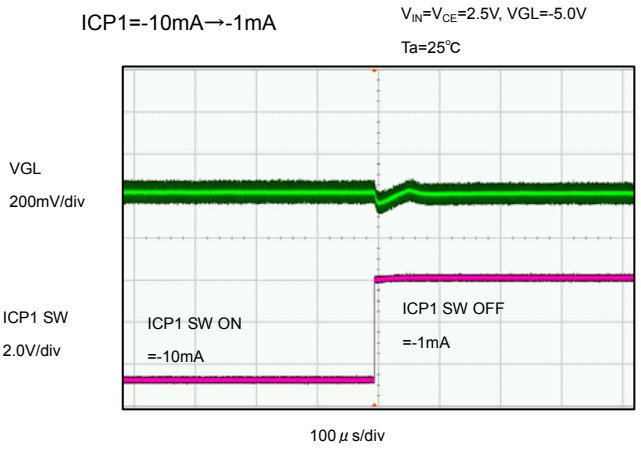
(14) Load Transient Response 1 vs. DC/DC Output (V_{OUT})





(15) Load Transient Response 2 vs. CP1 Output (VGL)



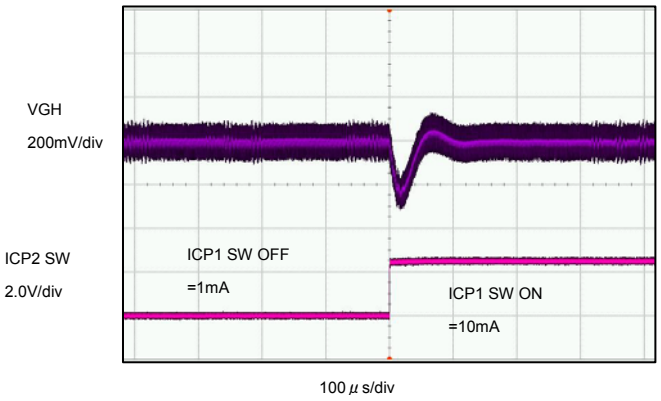


■TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(16) Load Transient Response 3 vs. CP2 Output (VGH)

ICP2=1mA→10mA

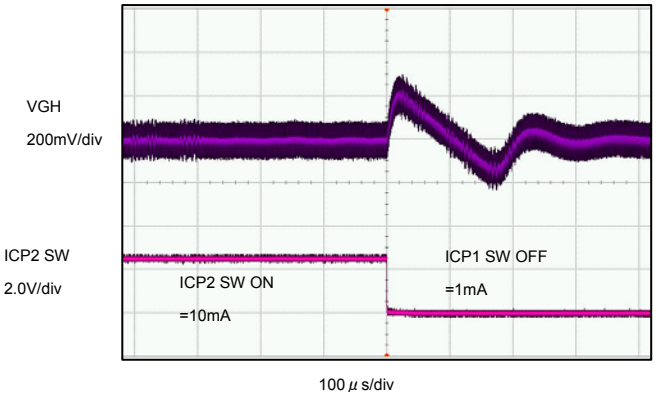
V_{IN}=V_{CE}=2.5V, VGH=12V
Ta=25℃



100 μ s/div

ICP2=10mA→1mA

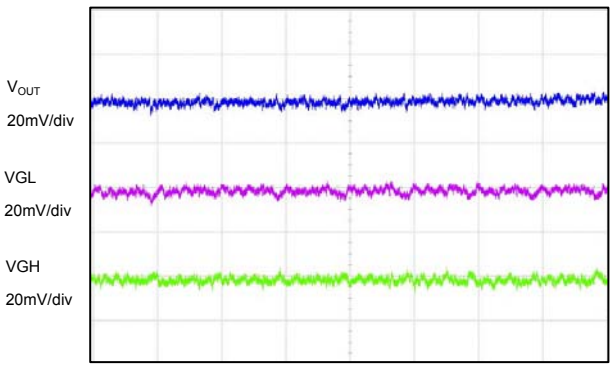
V_{IN}=V_{CE}=2.5V, VGH=12V
Ta=25℃



100 μ s/div

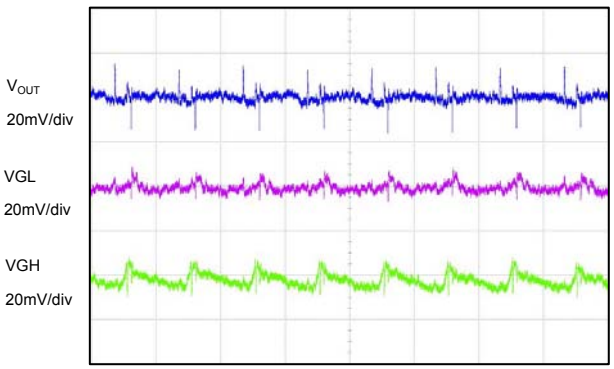
(17) Ripple Rejection Rat vs. Output Current

V_{IN}=V_{CE}=2.5V, V_{OUT}=9V, VGL=-5V, VGH=12V
Ta=25℃, I_{OUT}=0mA, ICP1=0mA, ICP2=0mA



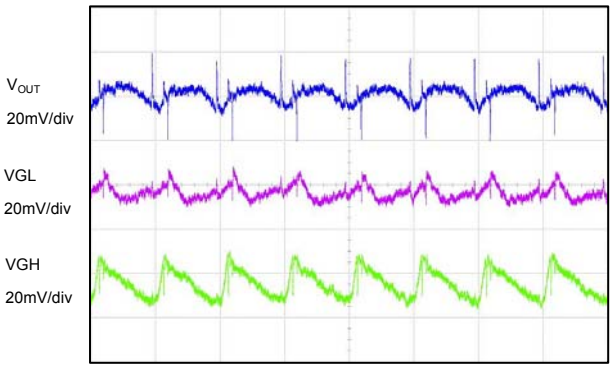
1 μ s/div

V_{IN}=V_{CE}=2.5V, V_{OUT}=9V, VGL=-5V, VGH=12V
Ta=25℃, I_{OUT}=50mA, ICP1=-5mA, ICP2=5mA



1 μ s/div

V_{IN}=V_{CE}=2.5V, V_{OUT}=9V, VGL=-5V, VGH=12V
Ta=25℃, I_{OUT}=100mA, ICP1=-10mA, ICP2=10mA



1 μ s/div

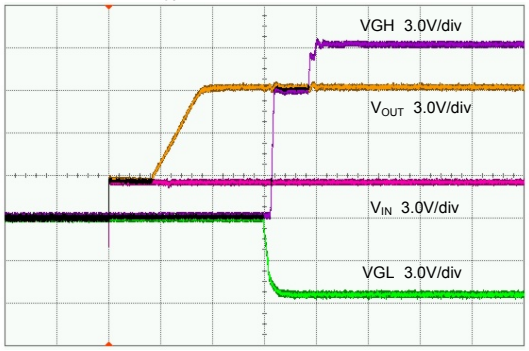
■TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(18) Start-up Sequence

V_{OUT} Monitor

V_{IN}=V_{CE}=2.5V, V_{OUT}=9V, VGL=-5V, VGH=12V

Ta=25℃, I_{OUT}=1mA, ICP1=-1mA, ICP2=1mA

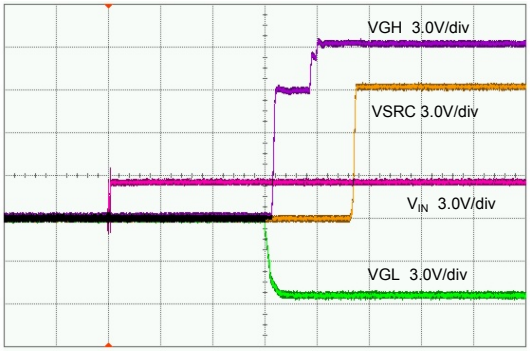


2.0ms/div

VSRC Monitor

V_{IN}=V_{CE}=2.5V, V_{OUT}=9V, VGL=-5V, VGH=12V

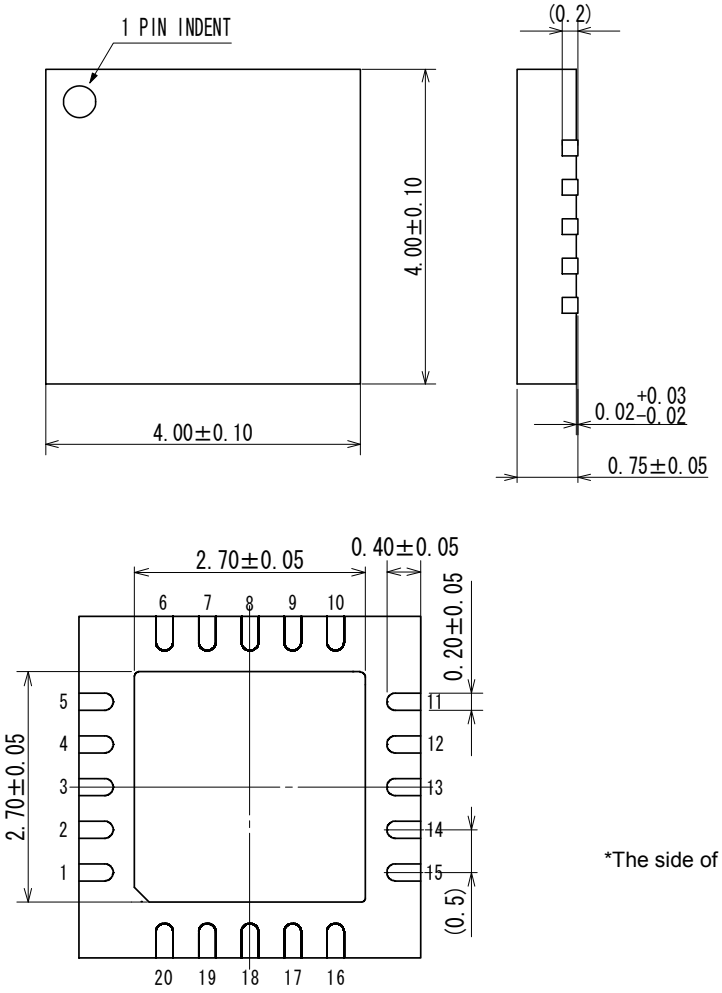
Ta=25℃, I_{OUT}=1mA, ICP1=-1mA, ICP2=1mA



2.0ms/div

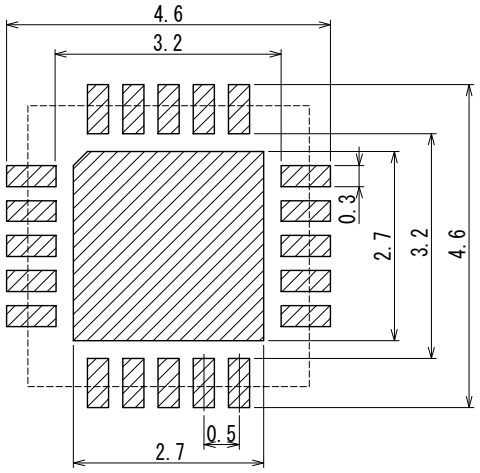
■PACKAGING INFORMATION

●QFN-20 (Unit: mm)

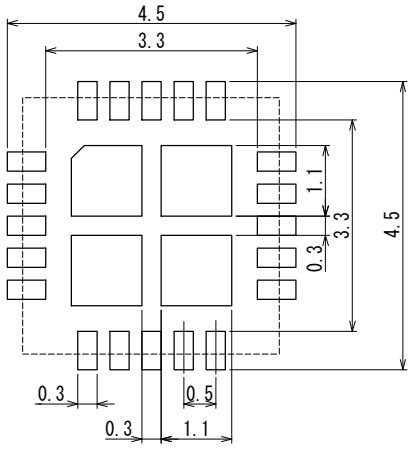


*The side of pins are not gilded, but nickel is used.

●QFN-20　Reference Pattern Layout (Unit: mm)



●QFN-20　Reference Metal Mask Design (Unit: mm)

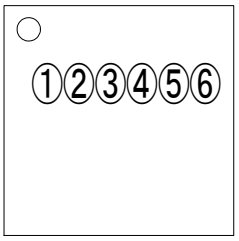


Solder Thickness：120μm (reference)

■MARKING RULE

QFN20

1pin



① represents product series

MARK	PRODUCT SERIES
0	XC9516******-G

② represents UVLO setting voltage and LX detect over current

MARK	UVLO VOLTAGE	LX DETECT OVER CURRENT	PRODUCT SERIES
A	Detect：1.87V, Hysteresis Width：0.44V	1.3A	XC9516A**A**-G

③④ represents V_{OUT} detect over voltage

MARK		V_{OUT} DETECT OVER VOLTAGE (e.g.)	PRODUCT SERIES
③	④		
2	1	21V	XC9516*21*** -G

⑤⑥ represents production lot number
01～09, 0A～0Z, 11･･･9Z, A1～A9, AA～Z9, ZA～ZZ repeated
（G, I, J, O, Q, W excluded）
*No character inversion used.

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